

PXT2222A

NPN switching transistors

2 April 2014

Product data sheet

1. General description

NPN switching transistor in a medium power flat lead SOT89 (SC-62/TO-243) Surface-Mounted Device (SMD) plastic package.

PNP complement: PXT2907A

2. Features and benefits

- High current: max. 600 mA
- Low voltage: max. 40 V

3. Applications

- Switching and linear amplification

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	40	V
I_C	collector current		-	-	600	mA
h_{FE}	DC current gain	$V_{CE} = 10 \text{ V}$; $I_C = 150 \text{ mA}$; $T_{amb} = 25 \text{ }^\circ\text{C}$; $\delta \leq 0.02$; $t_p \leq 300 \text{ } \mu\text{s}$; pulsed	100	-	300	

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	E	emitter	SOT89	sym123
2	C	collector		
3	B	base		



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6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PXT2222A	SOT89	plastic surface-mounted package; die pad for good heat transfer; 3 leads	SOT89

7. Marking

Table 4. Marking codes

Type number	Marking code [1]
PXT2222A	%1P

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

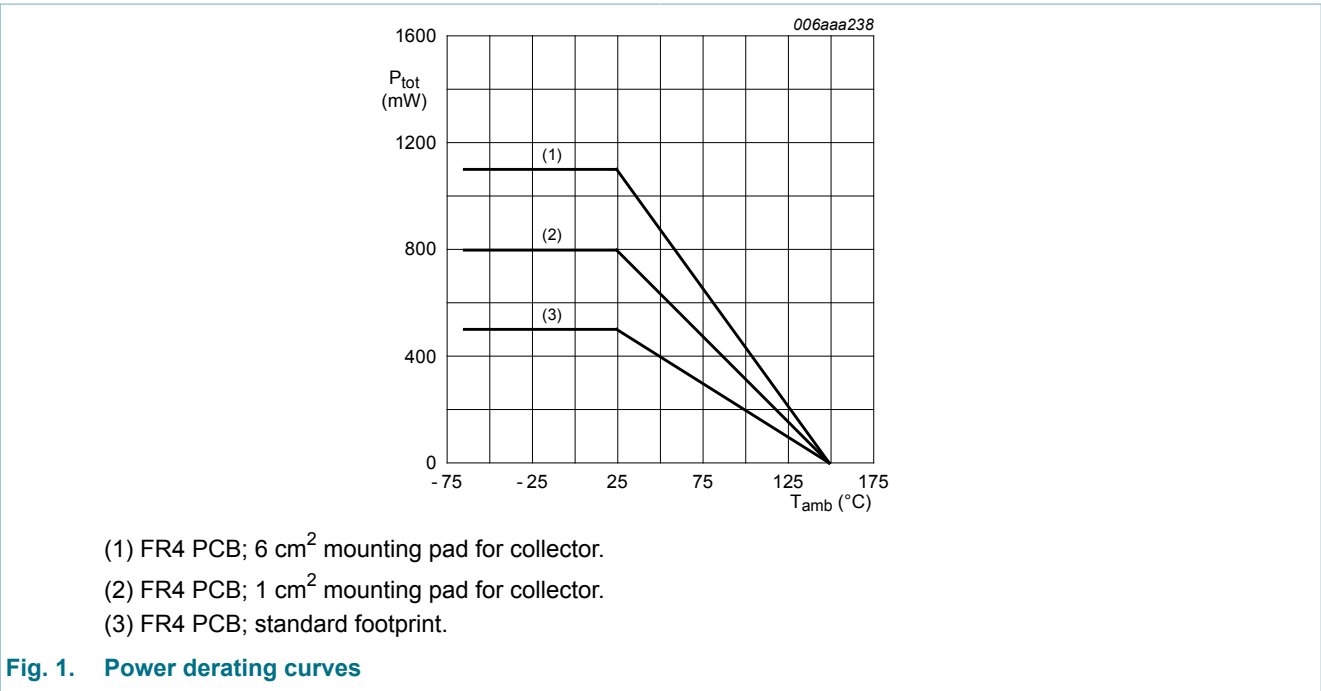
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	60	V
V_{CEO}	collector-emitter voltage	open base		-	40	V
V_{EBO}	emitter-base voltage	open collector		-	6	V
I_C	collector current	$t_p \leq 1$ ms; single pulse		-	600	mA
I_{CM}	peak collector current			-	800	mA
I_{BM}	peak base current			-	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	0.5	W
			[2]	-	0.8	W
			[3]	-	1.1	W
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-65	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Transistor mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Transistor mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm².

[3] Transistor mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm².



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	[1]	-	-	250	K/W
			[2]	-	-	156	K/W
			[3]	-	-	113	K/W
R _{th(j-sp)}	thermal resistance from junction to solder point			-	-	30	K/W

[1] Transistor mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[2] Transistor mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 1 cm².
[3] Transistor mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for collector 6 cm².

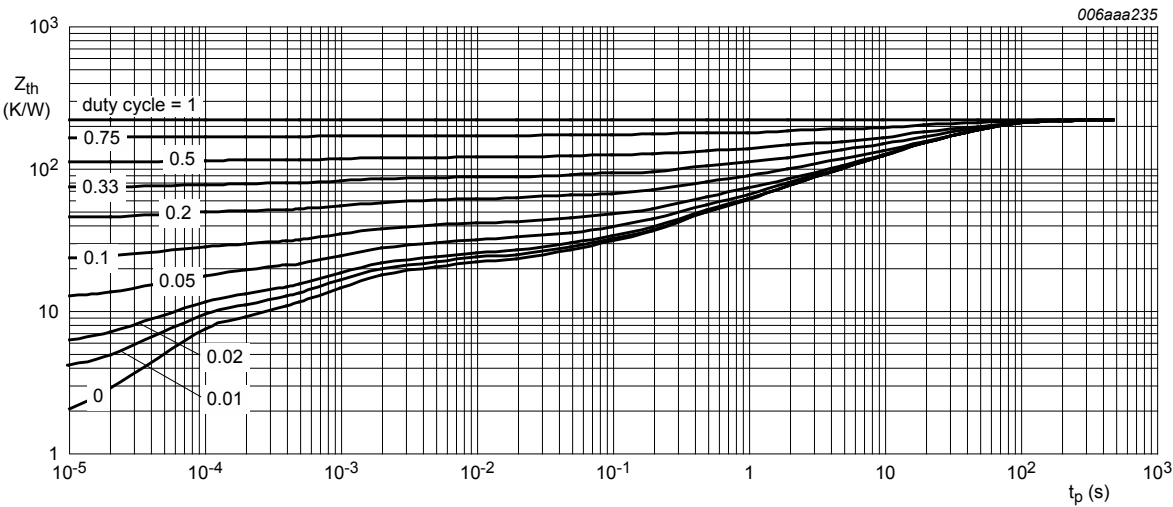


Fig. 2. Transient thermal impedance as a function of pulse time; typical values

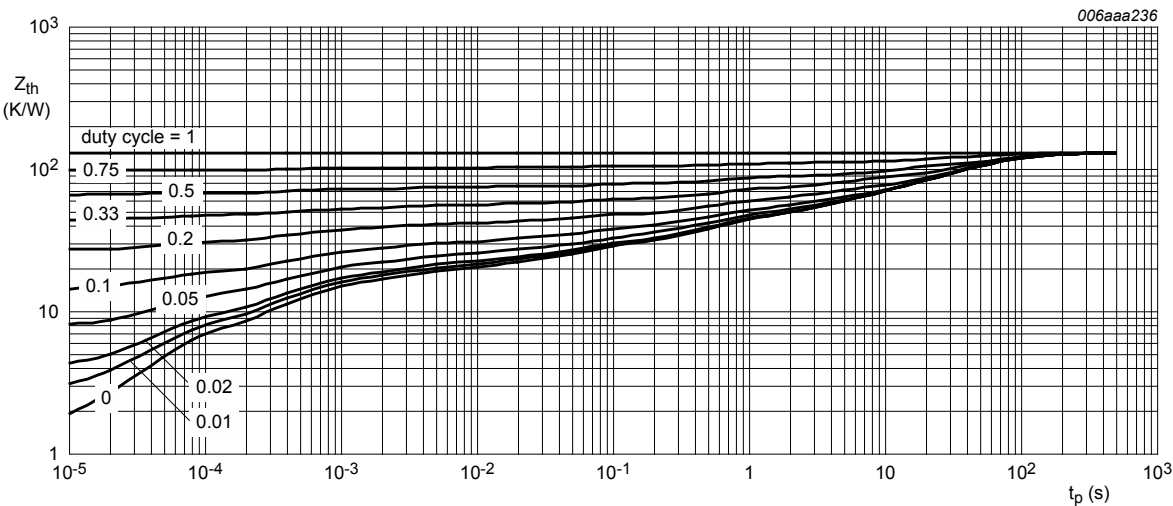


Fig. 3. Transient thermal impedance as a function of pulse time; typical values

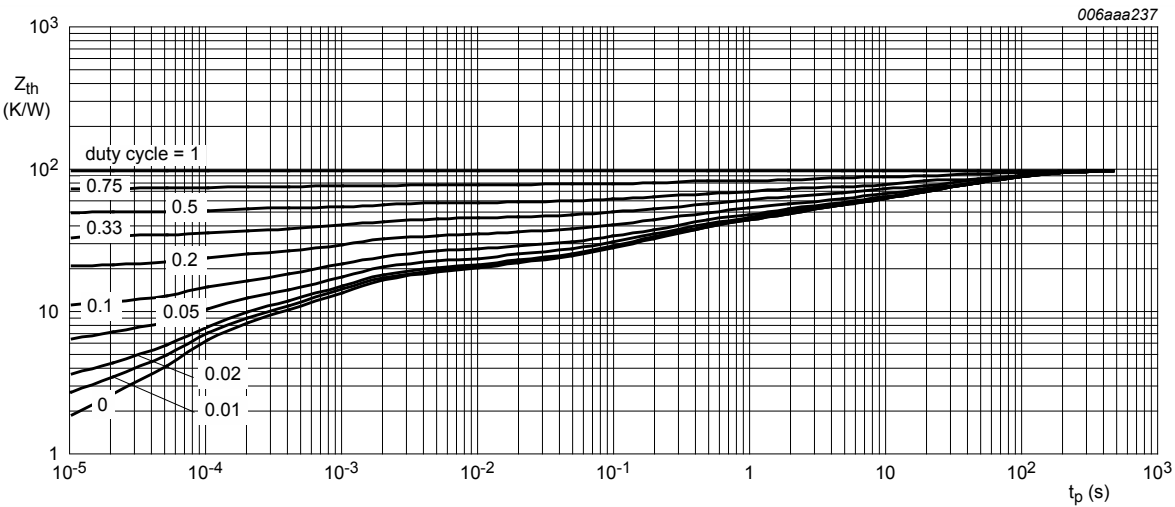


Fig. 4. Transient thermal impedance as a function of pulse time; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$V_{CB} = 60\text{ V}; I_E = 0\text{ A}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	10	nA
		$V_{CB} = 60\text{ V}; I_E = 0\text{ A}; T_j = 125\text{ }^{\circ}\text{C}$	-	-	10	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_C = 0\text{ A}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	10	nA
h_{FE}	DC current gain	$V_{CE} = 10\text{ V}; I_C = 0.1\text{ mA}; T_{amb} = 25\text{ }^{\circ}\text{C}$	35	-	-	
		$V_{CE} = 10\text{ V}; I_C = 1\text{ mA}; T_{amb} = 25\text{ }^{\circ}\text{C}$	50	-	-	
		$V_{CE} = 10\text{ V}; I_C = 10\text{ mA}; T_{amb} = 25\text{ }^{\circ}\text{C}$	75	-	-	
		$V_{CE} = 10\text{ V}; I_C = 10\text{ mA}; T_j = -55\text{ }^{\circ}\text{C}$	35	-	-	
		$V_{CE} = 1\text{ V}; I_C = 150\text{ mA}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^{\circ}\text{C}; \text{pulsed}$	50	-	-	
		$V_{CE} = 10\text{ V}; I_C = 150\text{ mA}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^{\circ}\text{C}; \text{pulsed}$	100	-	300	
		$V_{CE} = 10\text{ V}; I_C = 500\text{ mA}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02; T_{amb} = 25\text{ }^{\circ}\text{C}; \text{pulsed}$	40	-	-	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 150\text{ mA}; I_B = 15\text{ mA}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	300	mV
		$I_C = 500\text{ mA}; I_B = 50\text{ mA}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	1	V
V_{BEsat}	base-emitter saturation voltage	$I_C = 150\text{ mA}; I_B = 15\text{ mA}; T_{amb} = 25\text{ }^{\circ}\text{C}$	0.6	-	1.2	V
		$I_C = 500\text{ mA}; I_B = 50\text{ mA}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	2	V
t_d	delay time	$I_C = 150\text{ mA}; I_{Bon} = 15\text{ mA}; I_{Boff} = -15\text{ mA}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	15	ns
t_r	rise time		-	-	20	ns
t_{on}	turn-on time		-	-	35	ns
t_s	storage time		-	-	200	ns
t_f	fall time		-	-	60	ns
t_{off}	turn-off time		-	-	250	ns
C_C	collector capacitance	$V_{CB} = 10\text{ V}; I_E = 0\text{ A}; i_e = 0\text{ A}; f = 1\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	8	pF
C_E	emitter capacitance	$V_{EB} = 500\text{ mV}; I_C = 0\text{ A}; i_c = 0\text{ A}; f = 1\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	25	pF
f_T	transition frequency	$V_{CE} = 10\text{ V}; I_C = 20\text{ mA}; f = 100\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$	300	-	-	MHz
NF	noise figure	$V_{CE} = 5\text{ V}; I_C = 200\text{ }\mu\text{A}; R_S = 2\text{ k}\Omega; f = 1\text{ kHz}; B = 200\text{ Hz}; T_{amb} = 25\text{ }^{\circ}\text{C}$	-	-	4	dB

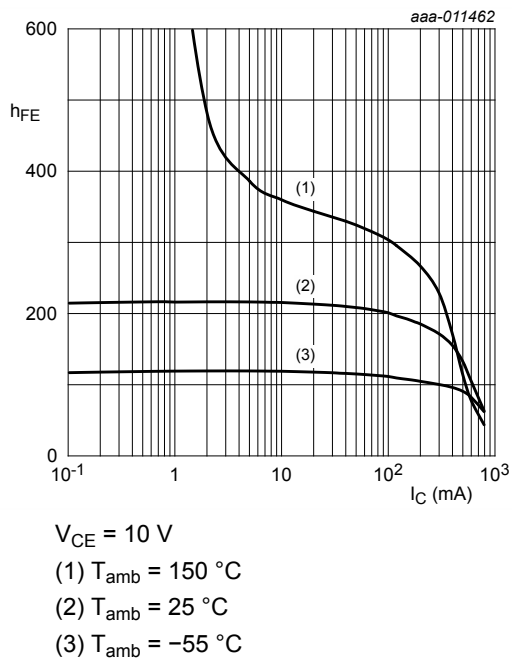


Fig. 5. DC current gain as a function of collector current; typical values

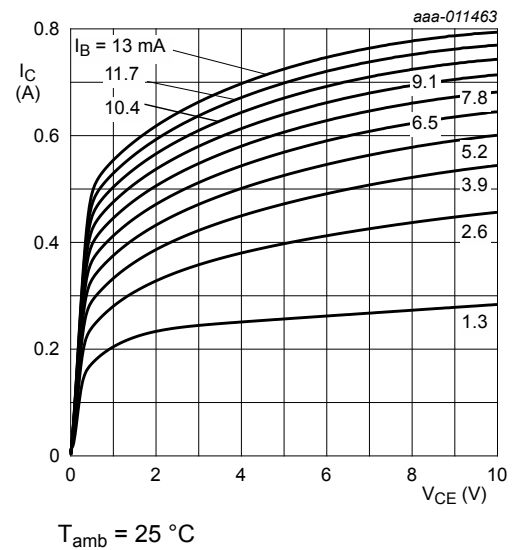


Fig. 6. Collector current as a function of collector-emitter voltage; typical values

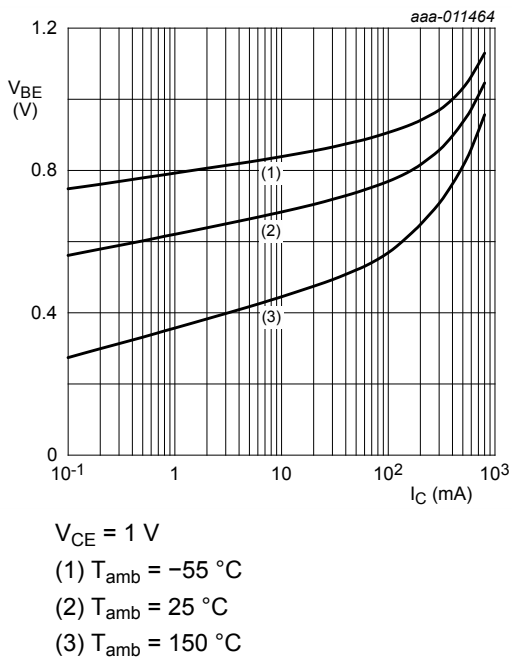


Fig. 7. Base-emitter voltage as a function of collector current; typical values

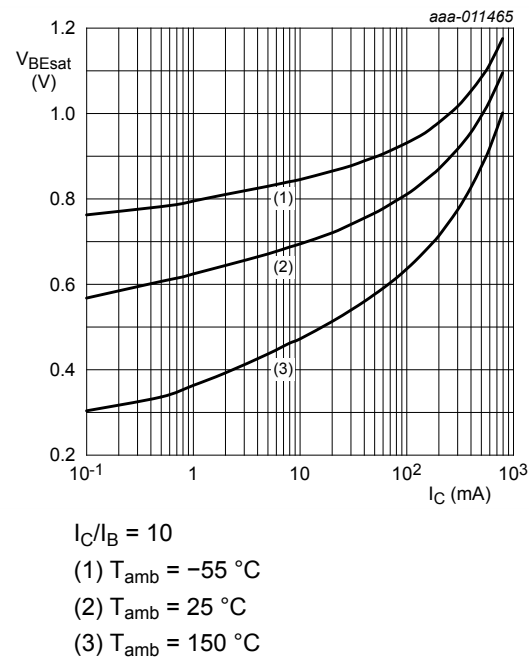
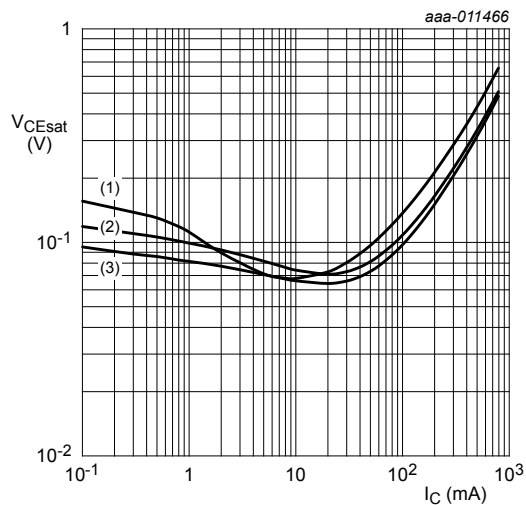


Fig. 8. Base-emitter saturation voltage as a function of collector current; typical values



$$I_C/I_B = 10$$

(1) $T_{amb} = 150^\circ\text{C}$

(2) $T_{amb} = 25^\circ\text{C}$

(3) $T_{amb} = -55^\circ\text{C}$

Fig. 9. Collector-emitter saturation voltage as a function of collector current; typical values

11. Test information

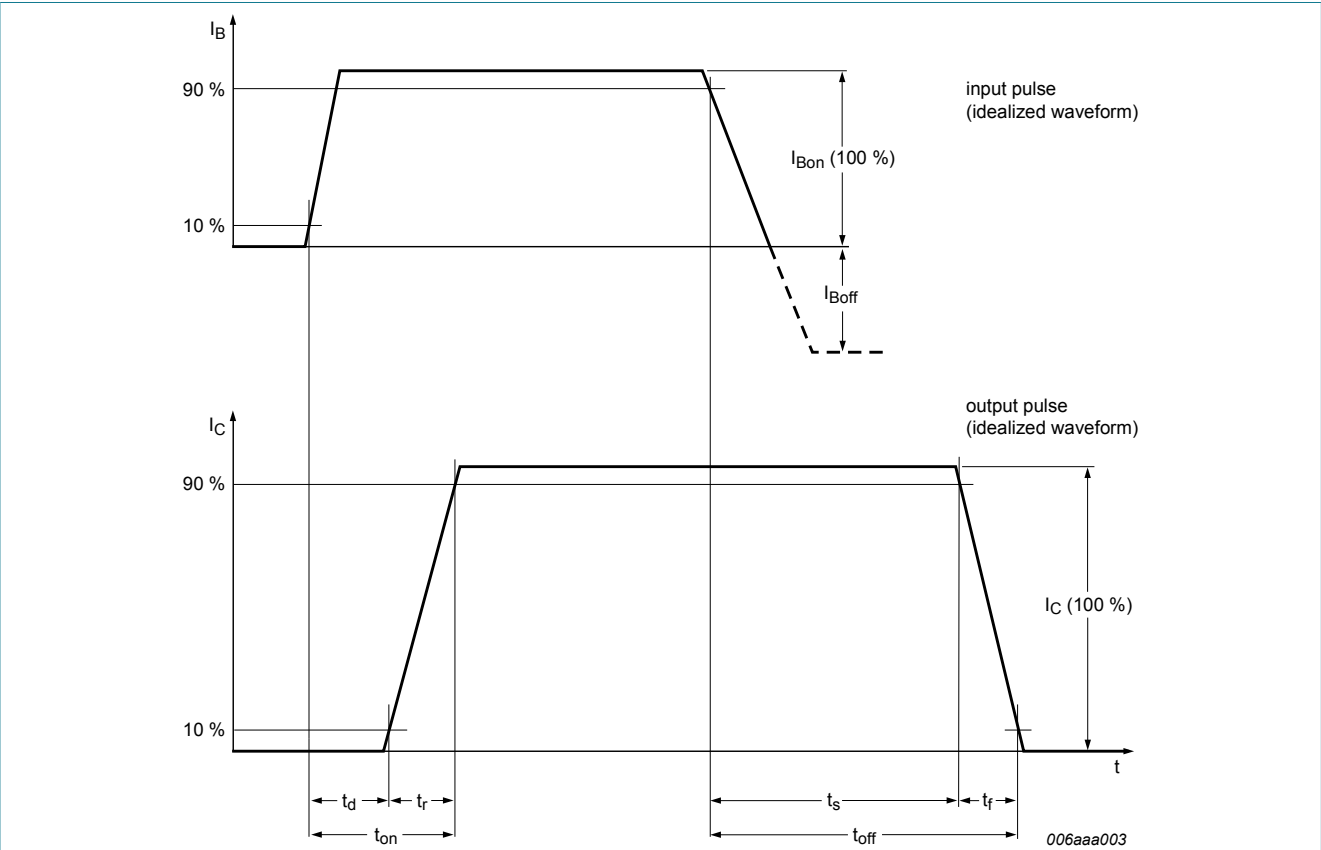


Fig. 10. BISS transistor switching time definition

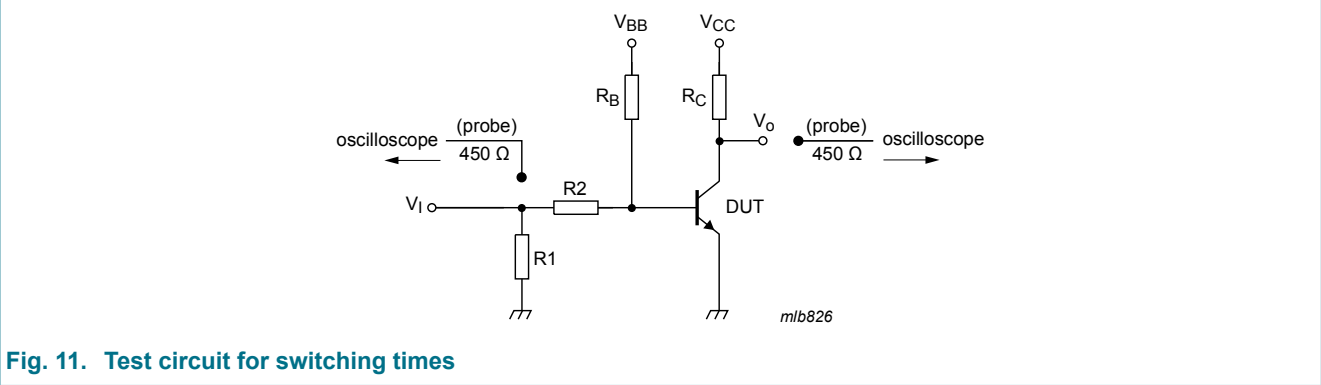


Fig. 11. Test circuit for switching times

12. Package outline

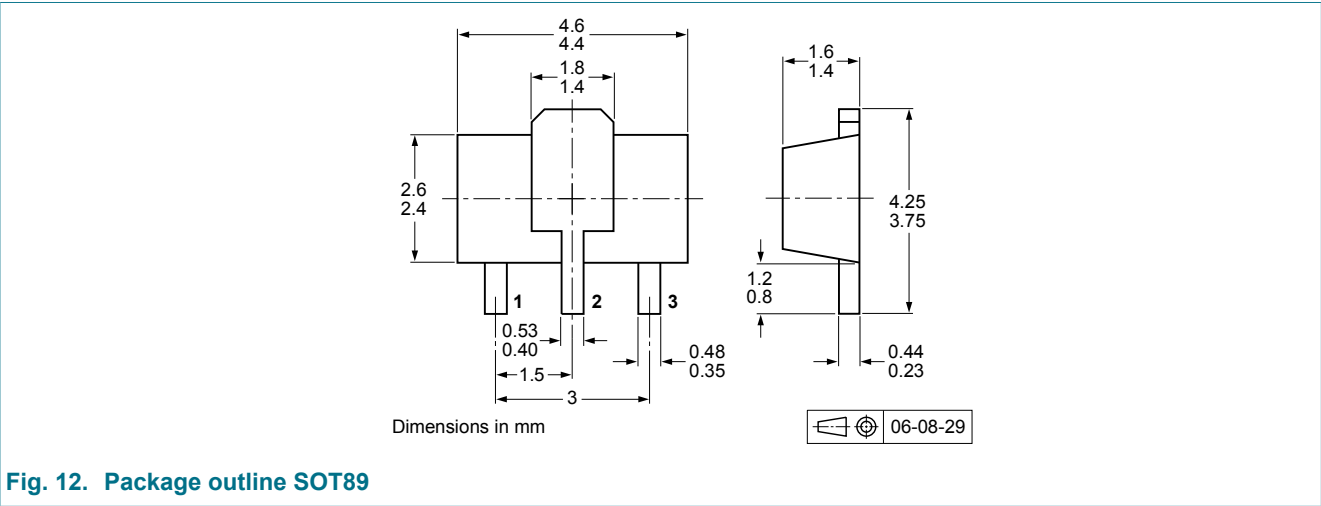


Fig. 12. Package outline SOT89

13. Soldering

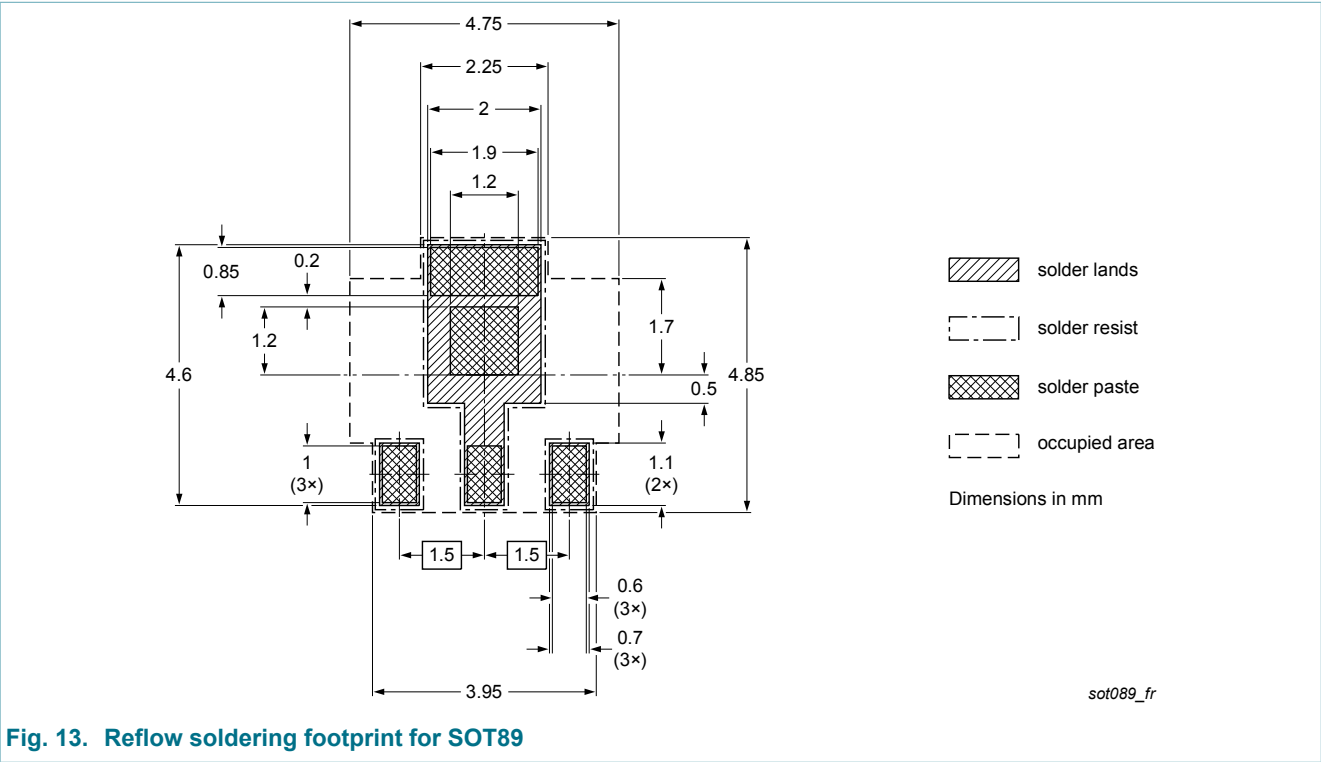
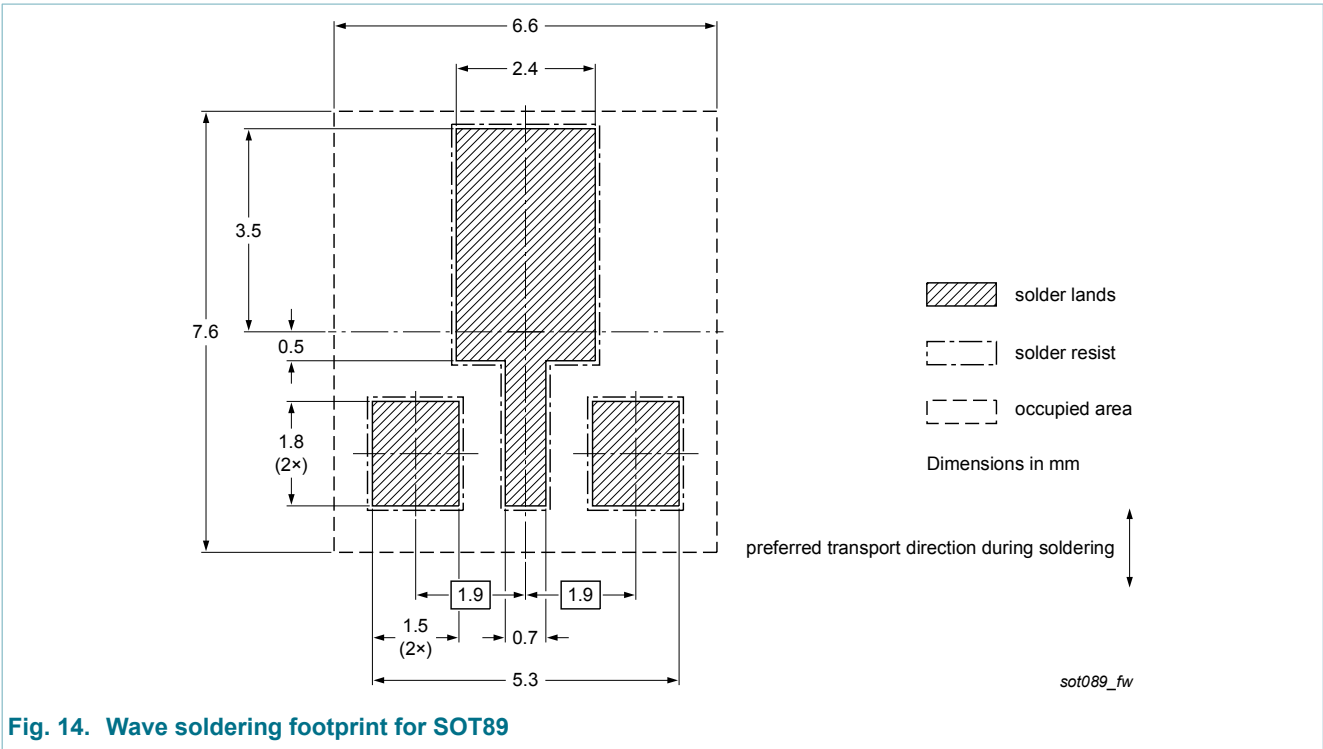


Fig. 13. Reflow soldering footprint for SOT89



14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PXT2222A v.5	20140402	Product data sheet	-	PXT2222A v.4
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • General description: updated. • Quick reference data: added. • Thermal characteristics: Figure 2 to 4 updated. • Limiting values: values of I_C, I_{CM} and I_{BM} parameters corrected. • Characteristics: Figures 5 to 9 added. • Soldering information: added. • Legal information: updated.			
PXT2222A v.4	20041122	Product specification	-	PXT2222A v.3
PXT2222A v.3	19990414	Product specification	-	PXT2222A v.2
PXT2222A v.2	19970505	Product specification	-	PXT2222A v.1
PXT2222A v.1	19940901	Product specification	-	-

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Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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